

RELIABILITY REPORT
FOR
MAX6576ZUT+
PLASTIC ENCAPSULATED DEVICES

September 1, 2011

MAXIM INTEGRATED PRODUCTS

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Approved by
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Quality Assurance
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Conclusion

The MAX6576ZUT+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX6576/MAX6577 are low-cost, low-current temperature sensors with a single-wire output. The MAX6576 converts the ambient temperature into a square wave with a period proportional to absolute temperature ($^{\circ}\text{K}$). The MAX6577 converts the ambient temperature into a square wave with a frequency proportional to absolute temperature. The MAX6576 offers accuracy of $\pm 3^{\circ}\text{C}$ at $+25^{\circ}\text{C}$, $\pm 4.5^{\circ}\text{C}$ at $+85^{\circ}\text{C}$, and $\pm 5^{\circ}\text{C}$ at $+125^{\circ}\text{C}$. The MAX6577 offers accuracy of $\pm 3^{\circ}\text{C}$ at $+25^{\circ}\text{C}$, $\pm 3.5^{\circ}\text{C}$ at $+85^{\circ}\text{C}$, and $\pm 4.5^{\circ}\text{C}$ at $+125^{\circ}\text{C}$. Both devices feature a single-wire output that minimizes the number of pins necessary to interface with a microprocessor. The period/frequency range of the output square wave can be selected by hard-wiring the two time-select pins (TS0, TS1) to either VDD or GND. The MAX6576/MAX6577 are available in space-saving 6-pin SOT23 packages.

II. Manufacturing Information

A. Description/Function:	SOT Temperature Sensors with Period/Frequency Output
B. Process:	S12
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Thailand
F. Date of Initial Production:	April 24, 1999

III. Packaging Information

A. Package Type:	6L SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1601-0067 / A
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	N/A
K. Single Layer Theta Jc:	N/A
L. Multi Layer Theta Ja:	230°C/W
M. Multi Layer Theta Jc:	76°C/W

IV. Die Information

A. Dimensions:	57 X 35 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)
Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 80 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 13.7 \times 10^{-9}$$

$$\lambda = 13.7 \text{ F.I.T. (60\% confidence level @ 25}^\circ\text{C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the Process results in a FIT Rate of 0.17 @ 25C and 3.00 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (ESD lot I4CBAQ001A D/C 9952, Latch-Up lot NRCBBA008A D/C 0349)

The MS14-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1500V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX6576ZUT+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0	I4CAAQ001D, D/C 9913

Note 1: Life Test Data may represent plastic DIP qualification lots.